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**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

*AF/2800*

In re the Application of: Smith et al.

Docket No.: TI-29811

Serial No.: 09/975,639

Art Unit: 2818

Filed: 10/11/01

Examiner: Hoang, Quoc

Title: Hydrogen Plasma Photoresist Strip And Polymeric Residue Cleanup Process  
For Low Dielectric Constant Materials

**REPLY UNDER 37 CFR 1.116 – EXPEDITED PROCEDURE  
TECHNOLOGY CENTER 2800**

October 22, 2003

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

<b>MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)</b>	
I hereby certify that the above correspondence is being deposited	
with the U.S. Postal Service on	
<u>10-22-03</u>	as First Class Mail in an
envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450	
<u>Karen Vertz</u>	<u>10-22-03</u>
Karen Vertz	Date

In response to the Office Action, dated 08/25/03, in the above-identified patent application, please make the following amendments. They are respectfully submitted as a full and complete response to that Action. Charge any required fees to the deposit account of Texas Instruments Incorporated, Account No. 0668.

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OCT 29 2003  
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